

In re Application of:
Keith Weinstein
Application No.: 10/601,139
Filed: June 20, 2003
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Atty Docket No.: PMW1110-2

Amendments to the Claims

Please amend claims 2-7, 10, 11 and 18 as indicated in the listing of claims.

Please cancel claim 17 without prejudice and disclaimer.

Claim 8 was previously canceled without prejudice.

Claims 1, 3-7 and 9 are allowed.

The listing of claims will replace all prior versions, and listings of claims in the application.

Listing of Claims:

1. (Previously presented) A solder composition for assembling, repairing or sizing jewelry comprising of about 25% to 92% by weight gold and about 2% to 14% by weight of an alloy consisting of gallium, indium, and copper in a respective weight ratio of approximately 6:3:1, wherein the solder composition has a melting temperature in a range from about 1000°F to about 1550°F.

2. (Currently amended) ~~A~~ The solder composition ~~according to~~ of claim 1, wherein the about 25% to 92% by weight gold further comprising comprises a mixture of about 8% to ~~80~~75% silver, about 1% to 66% copper, about 5% to 31% zinc and about 0% to 35% nickel.

3. (Currently amended) ~~A~~ The solder composition ~~according to~~ of claim 1, wherein the composition is about 25% by weight gold.

4. (Currently amended) ~~A~~ The solder composition ~~according to~~ of claim 1, wherein the composition is about 41.6% by weight gold.

5. (Currently amended) ~~A~~ The solder composition ~~according to~~ of claim 1, wherein the composition is about 58.3% by weight gold.

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6. (Currently amended) A The solder composition according to of claim 1, wherein the composition is about 75% by weight gold.

7. (Currently amended) A The solder composition according to of claim 1, wherein the composition is about 91.6% by weight gold.

8. (Canceled).

9. (Previously presented) A solder composition according to claim 1, wherein the solder composition has a melting temperature in the range from about 1100°F to 1550°F.

10. (Currently amended) An alloy for lowering the melting point of a gold solder comprising ~~about 2% to 14% by weight~~ gallium, indium and copper in a respective weight ratio of approximately 6:3:1, wherein the alloy is about 2% to 14% by weight of the solder, wherein the solder has a reduced melting temperature as compared to a solder not having the alloy, and wherein the alloy and the solder are free of palladium.

11. (Currently amended) The gold solder according to claim 18, wherein the gold solder further comprising comprises a mixture of about 8% to 80% silver, about 1% to 66% copper, about 5% to 31% zinc and about 0% to 35% nickel.

12. (Previously presented) The gold solder according to claim 18, wherein the solder is about 25% by weight gold.

13. (Previously presented) The gold solder according to claim 18, wherein the solder is about 41.6% by weight gold.

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14. (Previously presented) The gold solder according to claim 18, wherein the solder is about 58.3% by weight gold.

15. (Previously presented) The gold solder according to claim 18, wherein the solder is about 75% by weight gold.

16. (Previously presented) The gold solder according to claim 18, wherein the solder is about 91.6% by weight gold.

17. (Canceled).

18. (Currently amended) A gold solder composition comprising ~~of~~ about 25% to 92% by weight gold and about 2% to 14% by weight of an alloy for lowering the melting point of the solder comprising, wherein the alloy comprises about 2% to 14% by weight gallium, indium and copper in a respective weight ratio of approximately 6:3:1, and wherein the solder has a melting temperature in the range of about 1000°F to 1550°F.

19. (Previously presented) The gold solder according to claim 18, wherein the solder has a melting temperature in the range from about 1100°F to 1550°F.